



# L3G4200D

## MEMS motion sensor: ultra-stable three-axis digital output gyroscope

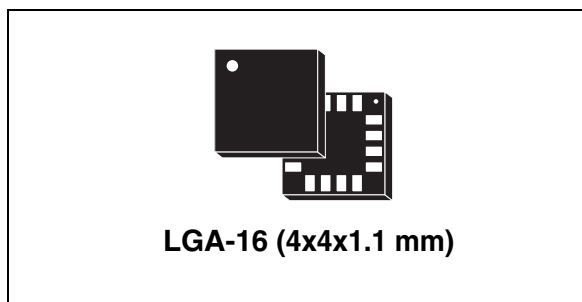
Preliminary data

### Features

- Three selectable full scales (250/500/2000 dps)
- I<sup>2</sup>C/SPI digital output interface
- 16 bit-rate value data output
- 8-bit temperature data output
- Two digital output lines (interrupt and data ready)
- Integrated low- and high-pass filters with user-selectable bandwidth
- Ultra-stable over temperature and time
- Wide supply voltage: 2.4 V to 3.6 V
- Low voltage-compatible IOs (1.8 V)
- Embedded power-down and sleep mode
- Embedded temperature sensor
- Embedded FIFO
- High shock survivability
- Extended operating temperature range (-40 °C to +85 °C)
- ECOPACK<sup>®</sup> RoHS and “Green” compliant

### Applications

- Gaming and virtual reality input devices
- Motion control with MMI (man-machine interface)
- GPS navigation systems
- Appliances and robotics



### Description

The L3G4200D is a low-power three-axis angular rate sensor able to provide unprecedented stability of zero rate level and sensitivity over temperature and time. It includes a sensing element and an IC interface capable of providing the measured angular rate to the external world through a digital interface (I<sup>2</sup>C/SPI).

The sensing element is manufactured using a dedicated micro-machining process developed by STMicroelectronics to produce inertial sensors and actuators on silicon wafers.

The IC interface is manufactured using a CMOS process that allows a high level of integration to design a dedicated circuit which is trimmed to better match the sensing element characteristics.

The L3G4200D has a full scale of  $\pm 250/\pm 500/\pm 2000$  dps and is capable of measuring rates with a user-selectable bandwidth.

The L3G4200D is available in a plastic land grid array (LGA) package and can operate within a temperature range of -40 °C to +85 °C.

Table 1. Device summary

Order code	Temperature range (°C)	Package	Packing
L3G4200D	-40 to +85	LGA-16 (4x4x1.1 mm)	Tray
L3G4200DTR	-40 to +85	LGA-16 (4x4x1.1 mm)	Tape and reel

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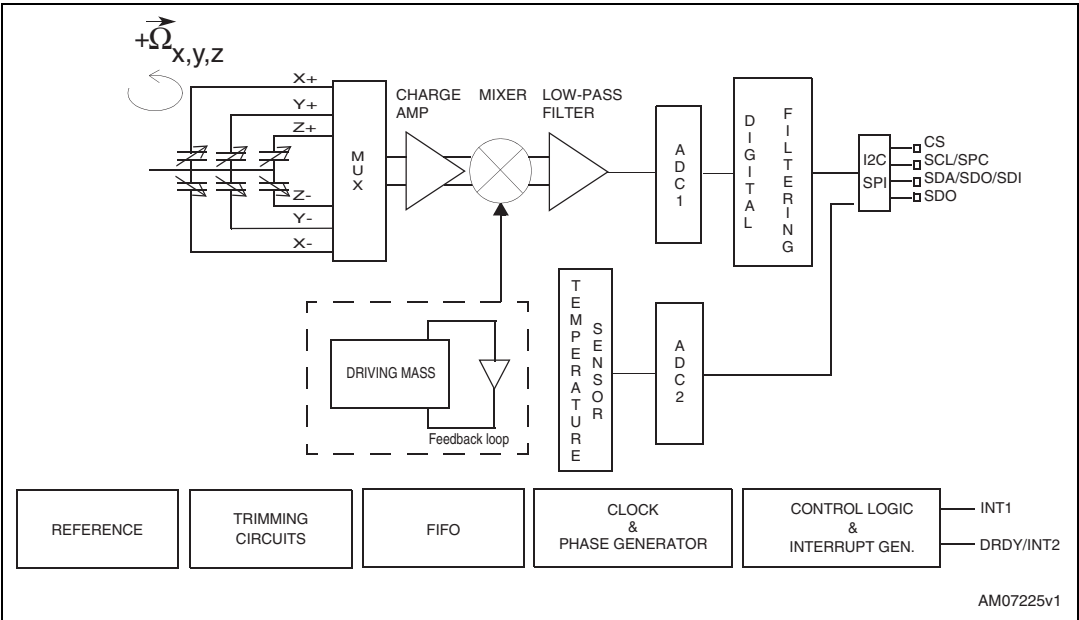
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# 1 Block diagram and pin description

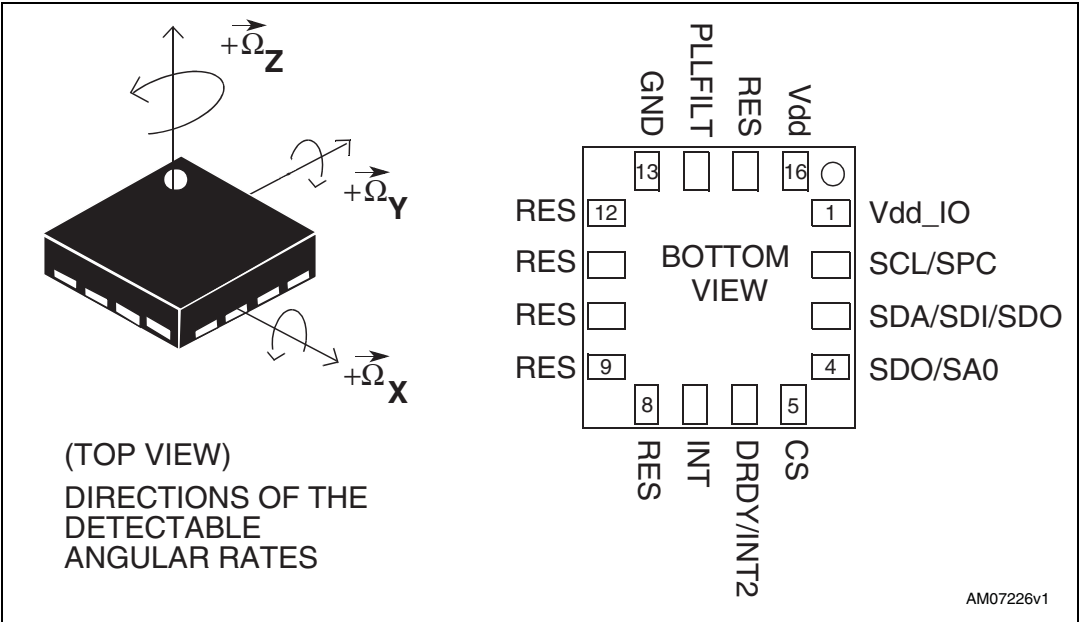
Figure 1. Block diagram



The vibration of the structure is maintained by drive circuitry in a feedback loop. The sensing signal is filtered and appears as a digital signal at the output.

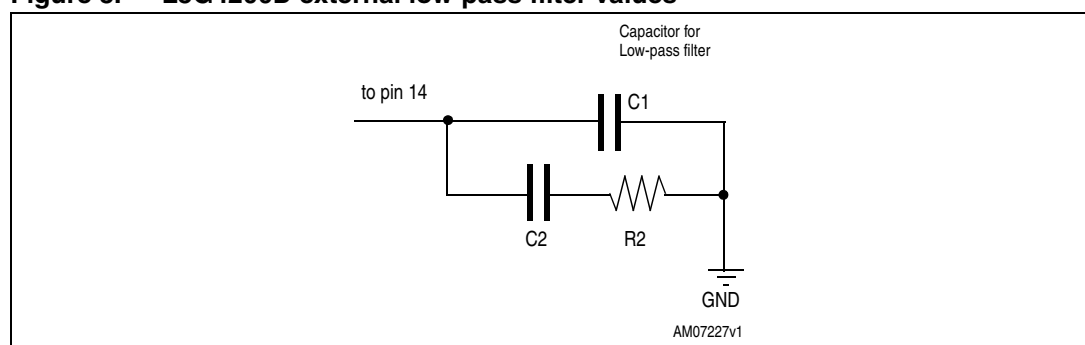
## 1.1 Pin description

Figure 2. Pin connection



**Table 2. Pin description**

Pin#	Name	Function
1	Vdd_IO	Power supply for I/O pins
2	SCL SPC	I <sup>2</sup> C serial clock (SCL) SPI serial port clock (SPC)
3	SDA SDI SDO	I <sup>2</sup> C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)
4	SDO SA0	SPI serial data output (SDO) I <sup>2</sup> C least significant bit of the device address (SA0)
5	CS	SPI enable I <sup>2</sup> C/SPI mode selection (1:SPI idle mode / I <sup>2</sup> C communication enabled; 0: SPI communication mode / I <sup>2</sup> C disabled)
6	DRDY/INT2	Data ready/FIFO interrupt
7	INT1	Programmable interrupt
8	Reserved	Connect to GND
9	Reserved	Connect to GND
10	Reserved	Connect to GND
11	Reserved	Connect to GND
12	Reserved	Connect to GND
13	GND	0 V supply
14	PLLFILT	Phase-locked loop filter (see <a href="#">Figure 3</a> )
15	Reserved	Connect to Vdd
16	Vdd	Power supply

**Figure 3. L3G4200D external low-pass filter values (a)**

a. Pin 14 PLLFILT maximum voltage level is equal to Vdd.



**Table 3. Filter values**

Parameter	Typical value
C1	10 nF
C2	470 nF
R2	10 k $\Omega$

## 2 Mechanical and electrical characteristics

### 2.1 Mechanical characteristics

Table 4. Mechanical characteristics @ Vdd = 3.0 V, T = 25 °C, unless otherwise noted<sup>(1)</sup>

Symbol	Parameter	Test condition	Min.	Typ. <sup>(2)</sup>	Max.	Unit
FS	Measurement range	User-selectable		±250		dps
				±500		
				±2000		
So	Sensitivity	FS = 250 dps		8.75		mdps/digit
		FS = 500 dps		17.50		
		FS = 2000 dps		70		
SoDr	Sensitivity change vs. temperature	From -40 °C to +85 °C		±2		%
DVoff	Digital zero-rate level	FS = 250 dps		±10		dps
		FS = 500 dps		±15		
		FS = 2000 dps		±75		
OffDr	Zero-rate level change vs. temperature <sup>(3)</sup>	FS = 250 dps		±0.03		dps/°C
		FS = 2000 dps		±0.04		dps/°C
NL	Non linearity <sup>(4)</sup>	Best fit straight line		0.2		% FS
DST	Self-test output change	FS = 250 dps		130		dps
		FS = 500 dps		200		
		FS = 2000 dps		530		
Rn	Rate noise density	BW = 50 Hz		0.03		dps/ sqrt(Hz)
ODR	Digital output data rate			100/200/ 400/800		Hz
Top	Operating temperature range		-40		+85	°C

1. The product is factory calibrated at 3.0 V. The operational power supply range is specified in [Table 5](#).

2. Typical specifications are not guaranteed.

3. Min/max values have been estimated based on the measurements of the current gyros in production.

4. Guaranteed by design.

## 2.2 Electrical characteristics

**Table 5. Electrical characteristics @ Vdd =3.0 V, T=25 °C, unless otherwise noted<sup>(1)</sup>**

Symbol	Parameter	Test condition	Min.	Typ. <sup>(2)</sup>	Max.	Unit
Vdd	Supply voltage		2.4	3.0	3.6	V
Vdd_IO	I/O pins supply voltage <sup>(3)</sup>		1.71		Vdd+0.1	V
Idd	Supply current			6.1		mA
IddSL	Supply current in sleep mode <sup>(4)</sup>	Selectable by digital interface		1.5		mA
IddPdn	Supply current in power-down mode	Selectable by digital interface		5		μA
Top	Operating temperature range		-40		+85	°C

1. The product is factory calibrated at 3.0 V.
2. Typical specifications are not guaranteed.
3. It is possible to remove Vdd maintaining Vdd\_IO without blocking the communication busses, in this condition the measurement chain is powered off.
4. Sleep mode introduces a faster turn-on time compared to power-down mode.

## 2.3 Temperature sensor characteristics

**Table 6. Temp. sensor characteristics @ Vdd =3.0 V, T=25 °C, unless otherwise noted<sup>(1)</sup>**

Symbol	Parameter	Test condition	Min.	Typ. <sup>(2)</sup>	Max.	Unit
TSDr	Temperature sensor output change vs. temperature			-1		°C/digit
TODR	Temperature refresh rate			1		Hz
Top	Operating temperature range		-40		+85	°C

1. The product is factory calibrated at 3.0 V.
2. Typical specifications are not guaranteed.

## 2.4 Communication interface characteristics

### 2.4.1 SPI - serial peripheral interface

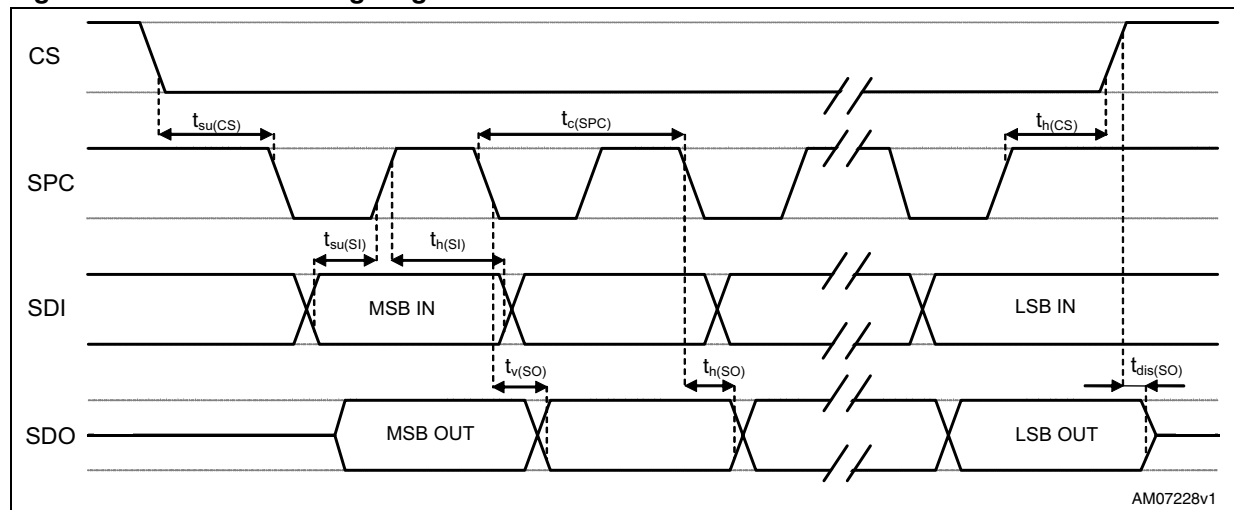
Subject to general operating conditions for Vdd and Top.

**Table 7. SPI slave timing values**

Symbol	Parameter	Value <sup>(1)</sup>		Unit
		Min.	Max.	
tc(SPC)	SPI clock cycle	100		ns
fc(SPC)	SPI clock frequency		10	MHz
tsu(CS)	CS setup time	5		ns
th(CS)	CS hold time	8		
tsu(SI)	SDI input setup time	5		
th(SI)	SDI input hold time	15		
tv(SO)	SDO valid output time		50	
th(SO)	SDO output hold time	6		
tdis(SO)	SDO output disable time		50	

1. Values are guaranteed at 10 MHz clock frequency for SPI with both 4 and 3 wires, based on characterization results; not tested in production.

**Figure 4. SPI slave timing diagram<sup>(b)</sup>**



b. Measurement points are done at 0.2·Vdd\_IO and 0.8·Vdd\_IO, for both input and output ports.

## 2.4.2 I<sup>2</sup>C - inter IC control interface

Subject to general operating conditions for Vdd and Top.

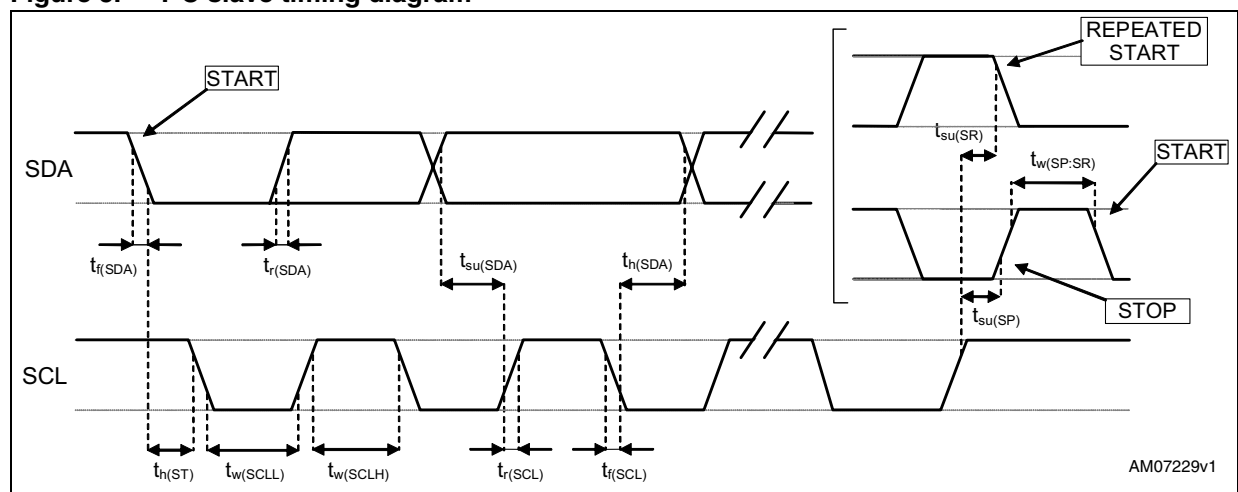
**Table 8. I<sup>2</sup>C slave timing values**

Symbol	Parameter	I <sup>2</sup> C standard mode <sup>(1)</sup>		I <sup>2</sup> C fast mode <sup>(1)</sup>		Unit
		Min	Max	Min	Max	
$f_{(SCL)}$	SCL clock frequency	0	100	0	400	kHz
$t_{w(SCLL)}$	SCL clock low time	4.7		1.3		$\mu$ s
$t_{w(SCLH)}$	SCL clock high time	4.0		0.6		
$t_{su(SDA)}$	SDA setup time	250		100		ns
$t_{h(SDA)}$	SDA data hold time	0	3.45	0	0.9	$\mu$ s
$t_{r(SDA)} t_{r(SCL)}$	SDA and SCL rise time		1000	$20 + 0.1C_b^{(2)}$	300	ns
$t_{f(SDA)} t_{f(SCL)}$	SDA and SCL fall time		300	$20 + 0.1C_b^{(2)}$	300	
$t_{h(ST)}$	START condition hold time	4		0.6		$\mu$ s
$t_{su(SR)}$	Repeated START condition setup time	4.7		0.6		
$t_{su(SP)}$	STOP condition setup time	4		0.6		
$t_{w(SP:SR)}$	Bus free time between STOP and START condition	4.7		1.3		

1. Data based on standard I<sup>2</sup>C protocol requirement; not tested in production.

2.  $C_b$  = total capacitance of one bus line, in pF.

**Figure 5. I<sup>2</sup>C slave timing diagram <sup>(c)</sup>**



c. Measurement points are done at 0.2·Vdd\_IO and 0.8·Vdd\_IO, for both ports.

## 2.5 Absolute maximum ratings

Any stress above that listed as “Absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**Table 9. Absolute maximum ratings**

Symbol	Ratings	Maximum value	Unit
Vdd	Supply voltage	-0.3 to 4.8	V
T <sub>STG</sub>	Storage temperature range	-40 to +125	°C
Sg	Acceleration <i>g</i> for 0.1 ms	10,000	<i>g</i>
ESD	Electrostatic discharge protection	2 (HBM)	kV



This is a mechanical shock sensitive device, improper handling can cause permanent damage to the part



This is an ESD sensitive device, improper handling can cause permanent damage to the part

## 2.6 Terminology

### 2.6.1 Sensitivity

An angular rate gyroscope is a device that produces a positive-going digital output for counterclockwise rotation around the sensitive axis considered. Sensitivity describes the gain of the sensor and can be determined by applying a defined angular velocity to it. This value changes very little over temperature and time.

### 2.6.2 Zero-rate level

Zero-rate level describes the actual output signal if there is no angular rate present. The zero-rate level of precise MEMS sensors is, to some extent, a result of stress to the sensor and, therefore, the zero-rate level can slightly change after mounting the sensor onto a printed circuit board or after exposing it to extensive mechanical stress. This value changes very little over temperature and time.

### 2.6.3 Stability over temperature and time

Thanks to the unique single driving mass approach and optimized design, ST gyroscopes are able to guarantee a perfect match of the MEMS mechanical mass and the ASIC interface, and deliver unprecedented levels of stability over temperature and time.

With Zero rate level and sensitivity performances, up to ten times better than equivalent products now available on the market, L3G4200D allows the user to avoid any further compensation and calibration during production for faster time to market, easy application implementation, higher performances and cost saving.

## 2.7 Soldering information

The LGA package is compliant with the ECOPACK<sup>®</sup>, RoHS and “Green” standard. It is qualified for soldering heat resistance according to JEDEC J-STD-020.

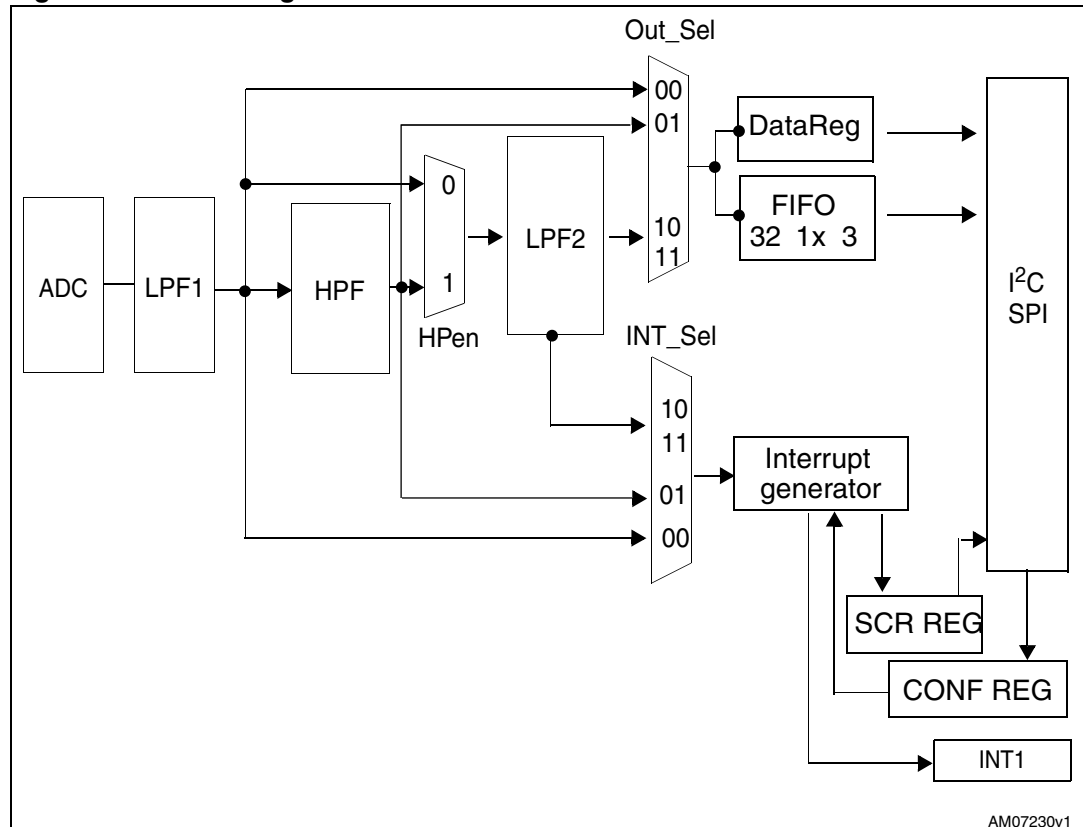
Leave “pin 1 Indicator” unconnected during soldering.

Land pattern and soldering recommendations are available at [www.st.com/](http://www.st.com/).

## 3 Main digital blocks

### 3.1 Block diagram

Figure 6. Block diagram



### 3.2 FIFO

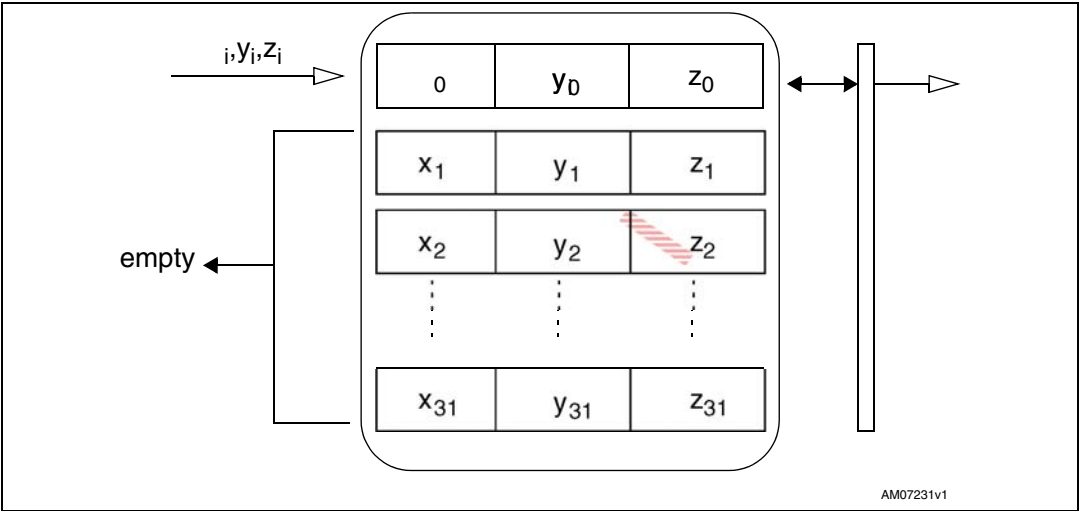
The L3G4200D embeds a 32-slot, 16-bit data FIFO for each of the three output channels: yaw, pitch, and roll. This allows consistent power saving for the system, as the host processor does not need to continuously poll data from the sensor. Instead, it can wake up only when needed and burst the significant data out from the FIFO. This buffer can work in five different modes. Each mode is selected by the FIFO\_MODE bits in the FIFO\_CTRL\_REG. Programmable watermark level, FIFO\_empty or FIFO\_Full events can be enabled to generate dedicated interrupts on the DRDY/INT2 pin (configured through CTRL\_REG3), and event detection information is available in FIFO\_SRC\_REG. The watermark level can be configured to WTM4:0 in FIFO\_CTRL\_REG.

#### 3.2.1 Bypass mode

In bypass mode, the FIFO is not operational and for this reason it remains empty. As illustrated in [Figure 7](#), only the first address is used for each channel. The remaining FIFO slots are empty. When new data is available, the old data is overwritten.



**Figure 7. Bypass mode**

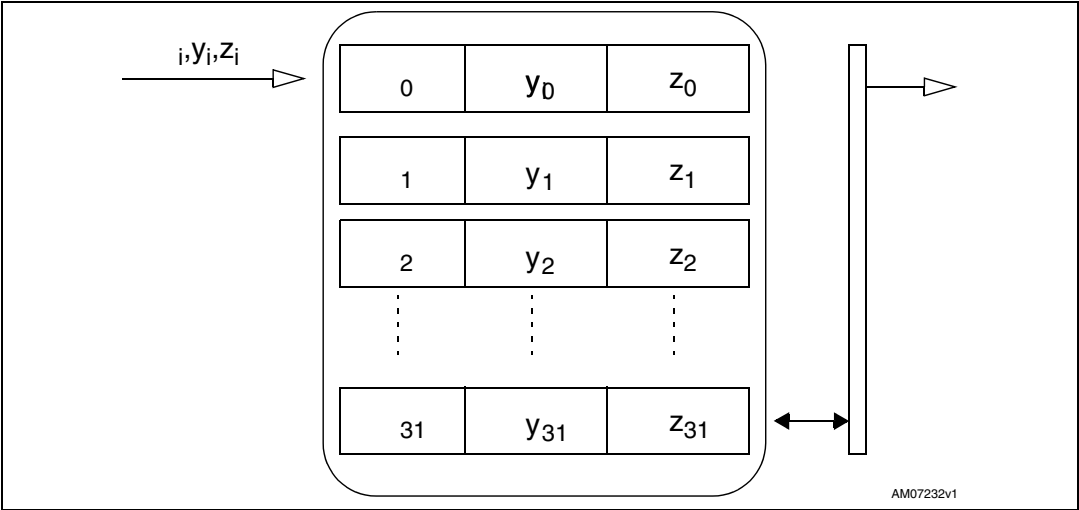


### 3.2.2 FIFO mode

In FIFO mode, data from the yaw, pitch, and roll channels are stored in the FIFO. A watermark interrupt can be enabled (I2\_WMK bit in CTRL\_REG3), which is triggered when the FIFO is filled to the level specified in the WTM 4:0 bits of FIFO\_CTRL\_REG. The FIFO continues filling until it is full (32 slots of 16-bit data for yaw, pitch, and roll). When full, the FIFO stops collecting data from the input channels. To restart data collection, it is necessary to write FIFO\_CTRL\_REG back to bypass mode.

FIFO mode is represented in [Figure 8](#).

**Figure 8. FIFO mode**



### 3.2.3 Stream mode

In stream mode, data from yaw, pitch, and roll measurements are stored in the FIFO. A watermark interrupt can be enabled and set as in FIFO mode. The FIFO continues filling until full (32 slots of 16-bit data for yaw, pitch, and roll). When full, the FIFO discards the

Stream mode is represented in [Figure 9](#).

Diagram illustrating a memory array structure. The array is indexed from 0 to 31. Each index  $i$  contains three values:  $y_i$ ,  $z_i$ , and  $x_i$ . The input  $i, y_i, z_i$  is shown entering the array. The output  $x_i$  is shown exiting the array and being directed to a trash can icon, indicating deletion or removal. A vertical bar on the right represents a memory management structure, with a double-headed arrow indicating interaction with the array.

In bypass-to-stream mode, the FIFO starts operating in bypass mode, and once a trigger event occurs (related to INT1\_CFG register events), the FIFO starts operating in stream mode (see [Figure 10](#)).

The diagram illustrates the Bypass mode and Stream mode of the AM07235v1 device.

**Bypass mode:** In this mode, the input  $i, y_i, z_i$  is processed by a block containing a table with rows  $0, y_0, z_0$  through  $x_{31}, y_{31}, z_{31}$ . The output is labeled "Empty".

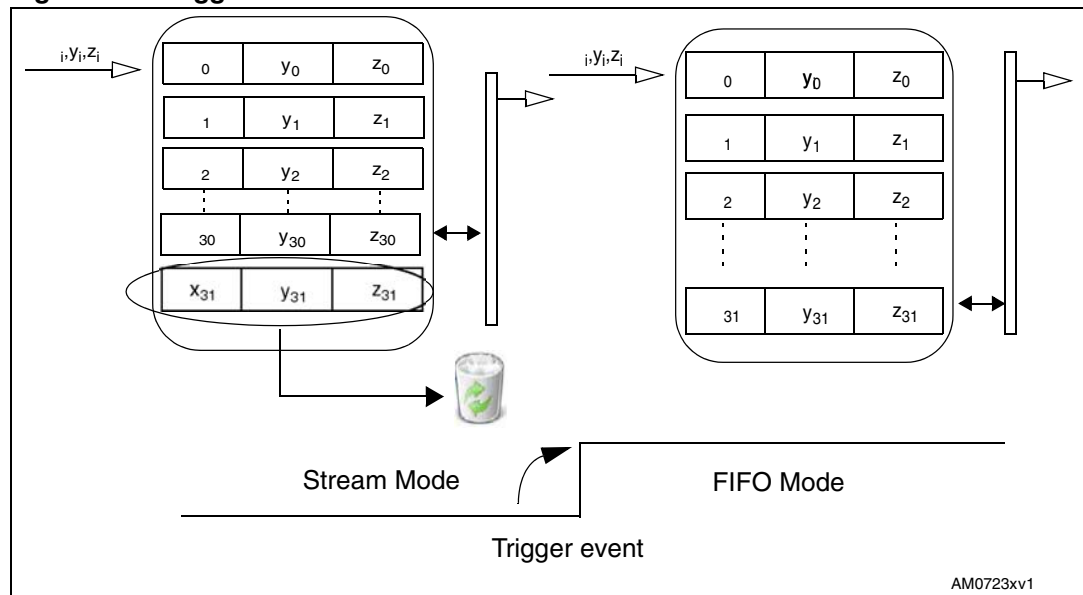
**Stream mode:** In this mode, the input  $i, y_i, z_i$  is processed by a block containing a table with rows  $0, y_0, z_0$  through  $x_{31}, y_{31}, z_{31}$ . The output is labeled "Stream mode" and is shown as a stream of data (represented by a can icon) being processed by a block.

A "Trigger event" is indicated by a curved arrow pointing from the Bypass mode to the Stream mode.

### 3.2.5 Stream-to-FIFO mode

In stream-to-FIFO mode, data from yaw, pitch, and roll measurements are stored in the FIFO. A watermark interrupt can be enabled on pin DRDY/INT2, setting the I2\_WTM bit in CTRL\_REG3, which is triggered when the FIFO is filled to the level specified in the WTM4:0 bits of FIFO\_CTRL\_REG. The FIFO continues filling until full (32 slots of 16-bit data for yaw, pitch, and roll). When full, the FIFO discards the older data as the new data arrives. Once a trigger event occurs (related to INT1\_CFG register events), the FIFO starts operating in FIFO mode (see [Figure 11](#)).

**Figure 11. Trigger stream mode**

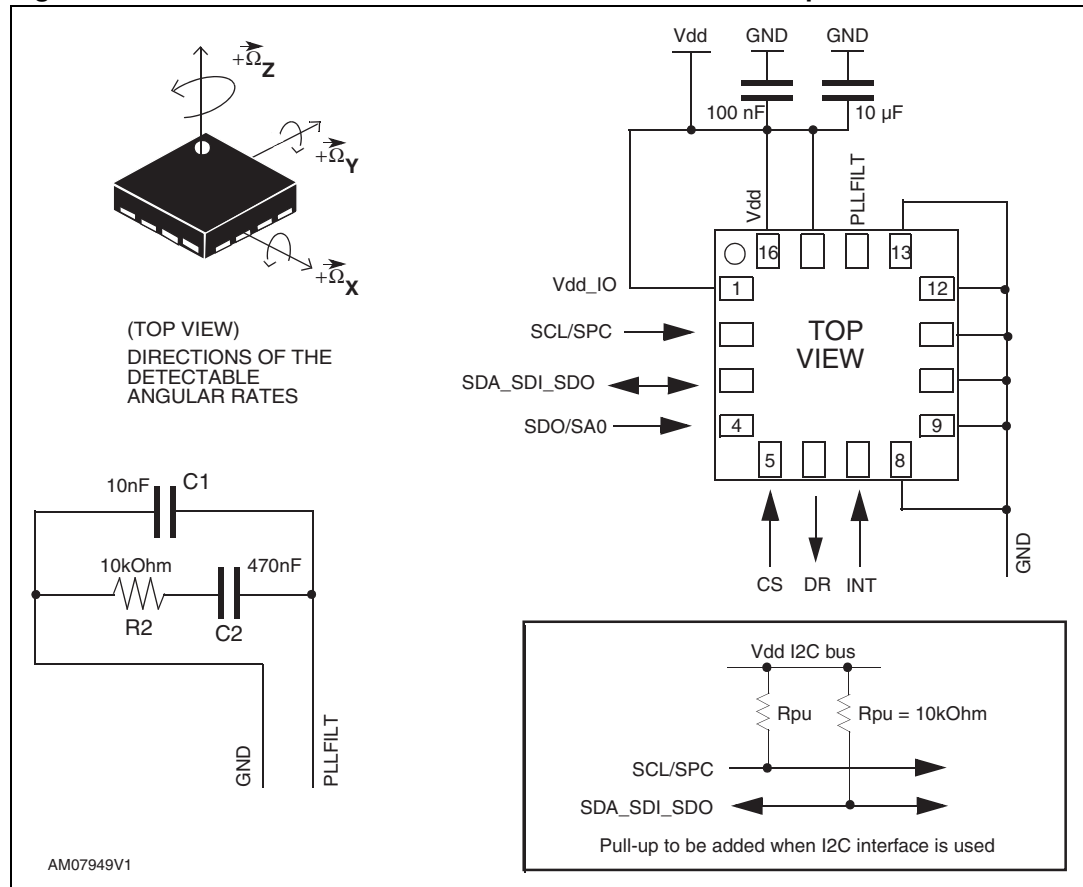


### 3.2.6 Retrieve data from FIFO

FIFO data is read through the OUT\_X, OUT\_Y and OUT\_Z registers. When the FIFO is in stream, trigger or FIFO mode, a read operation to the OUT\_X, OUT\_Y or OUT\_Z registers provides the data stored in the FIFO. Each time data is read from the FIFO, the oldest pitch, roll, and yaw data are placed in the OUT\_X, OUT\_Y and OUT\_Z registers and both single read and read\_burst (X, Y & Z with auto-incremental address) operations can be used. In read\_burst mode, when data included in OUT\_Z\_H is read, the system again starts to read information from addr OUT\_X\_L.

## 4 Application hints

Figure 12. L3G4200D electrical connections and external component values



Power supply decoupling capacitors (100 nF ceramic or polyester +10 μF) should be placed as near as possible to the device (common design practice).

If Vdd and Vdd\_IO are not connected together, power supply decoupling capacitors (100 nF and 10 μF between Vdd and common ground, 100 nF between Vdd\_IO and common ground) should be placed as near as possible to the device (common design practice).

The L3G4200D IC includes a PLL (phase locked loop) circuit to synchronize driving and sensing interfaces. Capacitors and resistors must be added at the **PLLFILT** pin (as shown in [Figure 12](#)) to implement a second-order low-pass filter. [Table 10](#) summarizes the PLL low-pass filter component values.

Table 10. PLL low-pass filter component values

Component	Value
C1	10 nF ± 10 %
C2	470 nF ± 10 %
R2	10 kΩ ± 10 %

## 5 Digital interfaces

The registers embedded in the L3G4200D may be accessed through both the I<sup>2</sup>C and SPI serial interfaces. The latter may be software-configured to operate either in 3-wire or 4-wire interface mode.

The serial interfaces are mapped onto the same pins. To select/exploit the I<sup>2</sup>C interface, the CS line must be tied high (i.e., connected to Vdd\_IO).

**Table 11. Serial interface pin description**

Pin name	Pin description
CS	SPI enable I <sup>2</sup> C/SPI mode selection (1:SPI idle mode / I <sup>2</sup> C communication enabled; 0: SPI communication mode / I <sup>2</sup> C disabled)
SCL/SPC	I <sup>2</sup> C serial clock (SCL) SPI serial port clock (SPC)
SDA/SDI/SDO	I <sup>2</sup> C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)
SDO	SPI serial data output (SDO) I <sup>2</sup> C least significant bit of the device address

### 5.1 I<sup>2</sup>C serial interface

The L3G4200D I<sup>2</sup>C is a bus slave. The I<sup>2</sup>C is employed to write data to registers whose content can also be read back.

The relevant I<sup>2</sup>C terminology is given in the table below.

**Table 12. I<sup>2</sup>C terminology**

Term	Description
Transmitter	The device which sends data to the bus
Receiver	The device which receives data from the bus
Master	The device which initiates a transfer, generates clock signals and terminates a transfer
Slave	The device addressed by the master

There are two signals associated with the I<sup>2</sup>C bus: the serial clock line (SCL) and the serial data line (SDA). The latter is a bidirectional line used for sending and receiving the data to/from the interface. Both lines must be connected to Vdd\_IO through an external pull-up resistor. When the bus is free both the lines are high.

The I<sup>2</sup>C interface is compliant with fast mode (400 kHz) I<sup>2</sup>C standards as well as with normal mode.

### 5.1.1 I<sup>2</sup>C operation

The transaction on the bus is started through a START (ST) signal. A START condition is defined as a HIGH to LOW transition on the data line while the SCL line is held HIGH. After this has been transmitted by the master, the bus is considered busy. The next byte of data transmitted after the start condition contains the address of the slave in the first 7 bits and the eighth bit tells whether the master is receiving data from the slave or transmitting data to the slave. When an address is sent, each device in the system compares the first 7 bits after a start condition with its address. If they match, the device considers itself addressed by the master.

The slave address (SAD) associated with the L3G4200D is 110100xb. The SDO pin can be used to modify the least significant bit (LSb) of the device address. If the SDO pin is connected to the voltage supply, LSb is '1' (address 1101001b). Otherwise, if the SDO pin is connected to ground, the LSb value is '0' (address 1101000b). This solution permits the connection and addressing of two different gyroscopes to the same I<sup>2</sup>C bus.

Data transfer with acknowledge is mandatory. The transmitter must release the SDA line during the acknowledge pulse. The receiver must then pull the data line LOW so that it remains stable low during the HIGH period of the acknowledge clock pulse. A receiver which has been addressed is obliged to generate an acknowledge after each byte of data received.

The I<sup>2</sup>C embedded in the L3G4200D behaves like a slave device, and the following protocol must be adhered to. After the START (ST) condition, a slave address is sent. Once a slave acknowledge (SAK) has been returned, an 8-bit sub-address is transmitted. The 7 LSb represent the actual register address while the MSB enables address auto-increment. If the MSb of the SUB field is 1, the SUB (register address) is automatically incremented to allow multiple data read/write.

The slave address is completed with a read/write bit. If the bit is '1' (read), a REPEATED START (SR) condition must be issued after the two sub-address bytes; if the bit is '0' (write) the master transmits to the slave with the direction unchanged. Table 13 describes how the SAD+read/write bit pattern is composed, listing all the possible configurations.

**Table 13. SAD+read/write patterns**

Command	SAD[6:1]	SAD[0] = SDO	R/W	SAD+R/W
Read	110100	0	1	11010001 (D1h)
Write	110100	0	0	11010000 (D0h)
Read	110100	1	1	11010011 (D3h)
Write	110100	1	0	11010010 (D2h)

**Table 14. Transfer when master is writing one byte to slave**

Master	ST	SAD + W		SUB		DATA		SP
Slave			SAK		SAK		SAK	

**Table 15. Transfer when master is writing multiple bytes to slave**

Master	ST	SAD + W		SUB		DATA		DATA		SP
Slave			SAK		SAK		SAK		SAK	

**Table 16. Transfer when master is receiving (reading) one byte of data from slave**

Master	ST	SAD + W		SUB		SR	SAD + R			NMAK	SP
Slave			SAK		SAK			SAK	DATA		

**Table 17. Transfer when master is receiving (reading) multiple bytes of data from slave**

Master	ST	SAD+W		SUB		SR	SAD+R			MAK		MAK		NMAK	SP
Slave			SAK		SAK			SAK	DATA		DATA		DATA		

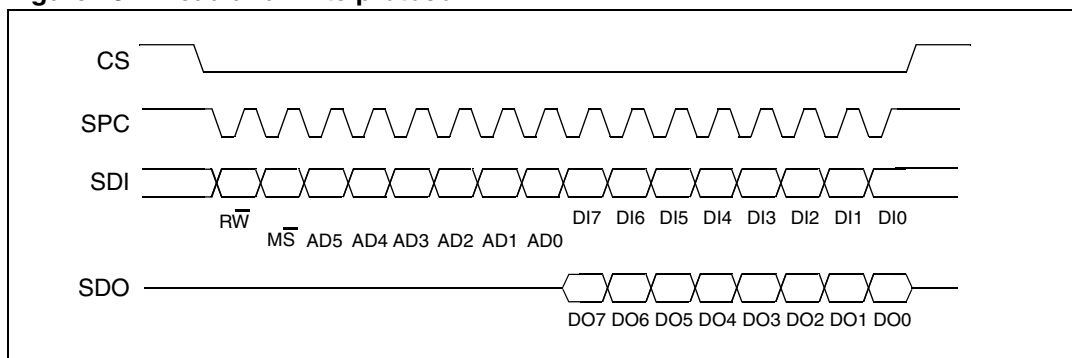
Data are transmitted in byte format (DATA). Each data transfer contains 8 bits. The number of bytes transferred per transfer is unlimited. Data is transferred with the most significant bit (MSb) first. If a receiver cannot receive another complete byte of data until it has performed some other function, it can hold the clock line SCL LOW to force the transmitter into a wait state. Data transfer only continues when the receiver is ready for another byte and releases the data line. If a slave receiver does not acknowledge the slave address (i.e., it is not able to receive because it is performing some real-time function) the data line must be left HIGH by the slave. The master can then abort the transfer. A LOW to HIGH transition on the SDA line while the SCL line is HIGH is defined as a STOP condition. Each data transfer must be terminated by the generation of a STOP (SP) condition.

In order to read multiple bytes, it is necessary to assert the most significant bit of the sub-address field. In other words, SUB(7) must be equal to 1, while SUB(6-0) represents the address of the first register to be read.

In the presented communication format, MAK is “master acknowledge” and NMAK is “no master acknowledge”.

## 5.2 SPI bus interface

The SPI is a bus slave. The SPI allows writing and reading of the device registers. The serial interface interacts with the external world through 4 wires: **CS**, **SPC**, **SDI**, and **SDO**.

**Figure 13. Read and write protocol**

**CS** is the serial port enable and is controlled by the SPI master. It goes low at the start of the transmission and returns to high at the end. **SPC** is the serial port clock and is controlled by the SPI master. It is stopped high when **CS** is high (no transmission). **SDI** and **SDO** are, respectively, the serial port data input and output. These lines are driven at the falling edge of **SPC** and should be captured at the rising edge of **SPC**.

Both the read register and write register commands are completed in 16 clock pulses, or in multiples of 8 in case of multiple read/write bytes. Bit duration is the time between two falling edges of **SPC**. The first bit (bit 0) starts at the first falling edge of **SPC** after the falling edge of **CS** while the last bit (bit 15, bit 23, etc.) starts at the last falling edge of **SPC** just before the rising edge of **CS**.

**Bit 0:**  $R\overline{W}$  bit. When 0, the data DI(7:0) is written to the device. When 1, the data DO(7:0) from the device is read. In the latter case, the chip drives **SDO** at the start of bit 8.

**Bit 1:**  $M\overline{S}$  bit. When 0, the address remains unchanged in multiple read/write commands. When 1, the address is auto-incremented in multiple read/write commands.

**Bit 2-7:** address AD(5:0). This is the address field of the indexed register.

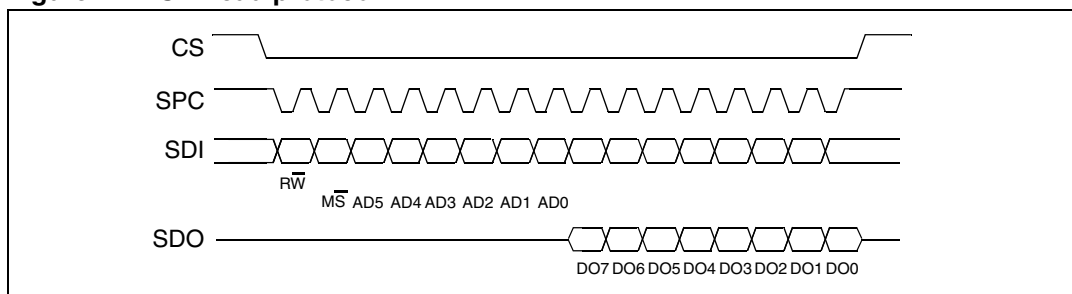
**Bit 8-15:** data DI(7:0) (write mode). This is the data that is written to the device (MSb first).

**Bit 8-15:** data DO(7:0) (read mode). This is the data that is read from the device (MSb first).

In multiple read/write commands, further blocks of 8 clock periods are added. When the  $M\overline{S}$  bit is 0, the address used to read/write data remains the same for every block. When the  $M\overline{S}$  bit is 1, the address used to read/write data is incremented at every block.

The function and the behavior of **SDI** and **SDO** remain unchanged.

### 5.2.1 SPI read

**Figure 14. SPI read protocol**



The SPI read command is performed with 16 clock pulses. A multiple byte read command is performed by adding blocks of 8 clock pulses to the previous one.

**Bit 0:** READ bit. The value is 1.

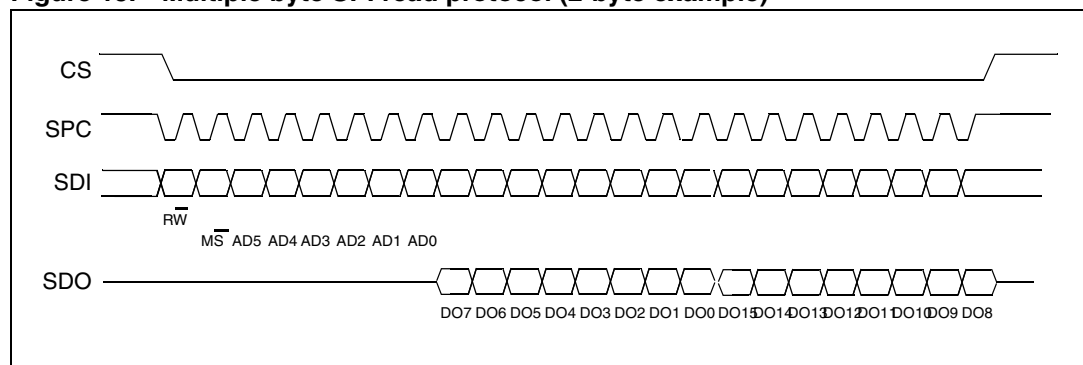
**Bit 1:**  $\overline{MS}$  bit. When 0, do not increment address; when 1, increment address in multiple reading.

**Bit 2-7:** address AD(5:0). This is the address field of the indexed register.

**Bit 8-15:** data DO(7:0) (read mode). This is the data that is read from the device (MSb first).

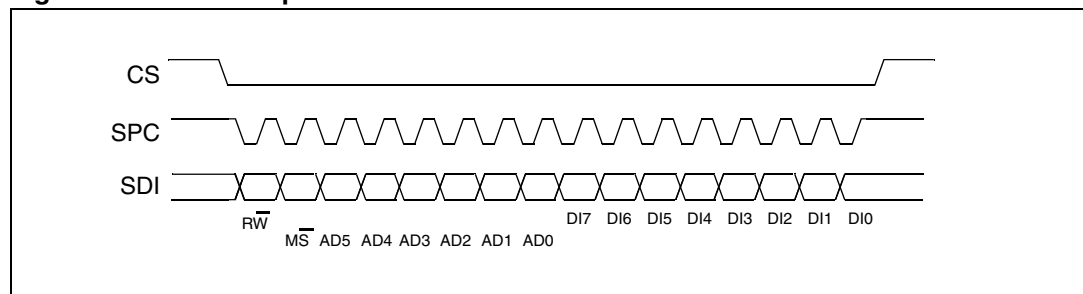
**Bit 16-...** : data DO(...-8). Further data in multiple byte reading.

**Figure 15. Multiple byte SPI read protocol (2-byte example)**



## 5.2.2 SPI write

**Figure 16. SPI write protocol**



The SPI write command is performed with 16 clock pulses. A multiple byte write command is performed by adding blocks of 8 clock pulses to the previous one.

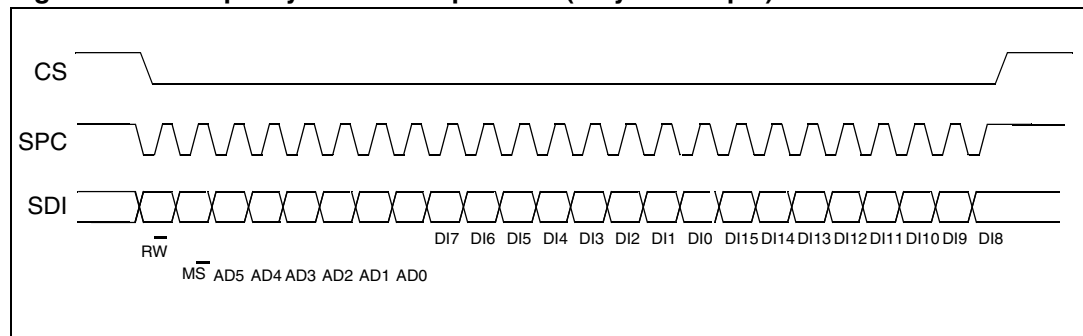
**Bit 0:** WRITE bit. The value is 0.

**Bit 1:**  $\overline{MS}$  bit. When 0, do not increment address; when 1, increment address in multiple writing.

**Bit 2-7:** address AD(5:0). This is the address field of the indexed register.

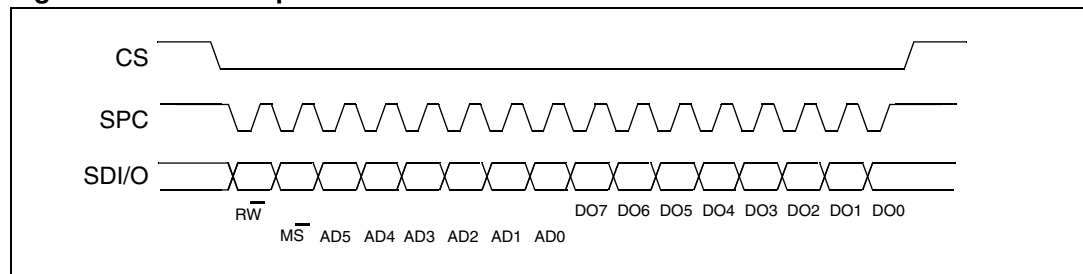
**Bit 8-15:** data DI(7:0) (write mode). This is the data that is written to the device (MSb first).

**Bit 16-...** : data DI(...-8). Further data in multiple byte writing.

**Figure 17. Multiple byte SPI write protocol (2-byte example)**

### 5.2.3 SPI read in 3-wire mode

3-wire mode is entered by setting the SIM (SPI serial interface mode selection) bit to 1 in CTRL\_REG2.

**Figure 18. SPI read protocol in 3-wire mode**

The SPI read command is performed with 16 clock pulses:

**Bit 0:** READ bit. The value is 1.

**Bit 1:**  $\overline{MS}$  bit. When 0, do not increment address; when 1, increment address in multiple reading.

**Bit 2-7:** address AD(5:0). This is the address field of the indexed register.

**Bit 8-15:** data DO(7:0) (read mode). This is the data that is read from the device (MSb first).

The multiple read command is also available in 3-wire mode.

## 6 Output register mapping

The table given below provides a listing of the 8 bit registers embedded in the device and the related addresses:

**Table 18. Register address map**

Name	Type	Register address		Default	Comment
		Hex	Binary		
Reserved	-	00-0E	-	-	
WHO_AM_I	r	0F	000 1111	11010011	
Reserved	-	10-1F	-	-	
CTRL_REG1	rw	20	010 0000	00000111	
CTRL_REG2	rw	21	010 0001	00000000	
CTRL_REG3	rw	22	010 0010	00000000	
CTRL_REG4	rw	23	010 0011	00000000	
CTRL_REG5	rw	24	010 0100	00000000	
REFERENCE	rw	25	010 0101	00000000	
OUT_TEMP	r	26	010 0110	output	
STATUS_REG	r	27	010 0111	output	
OUT_X_L	r	28	010 1000	output	
OUT_X_H	r	29	010 1001	output	
OUT_Y_L	r	2A	010 1010	output	
OUT_Y_H	r	2B	010 1011	output	
OUT_Z_L	r	2C	010 1100	output	
OUT_Z_H	r	2D	010 1101	output	
FIFO_CTRL_REG	rw	2E	010 1110	00000000	
FIFO_SRC_REG	r	2F	010 1111	output	
INT1_CFG	rw	30	011 0000	00000000	
INT1_SRC	r	31	011 0001	output	
INT1_TSH_XH	rw	32	011 0010	00000000	
INT1_TSH_XL	rw	33	011 0011	00000000	
INT1_TSH_YH	rw	34	011 0100	00000000	
INT1_TSH_YL	rw	35	011 0101	00000000	
INT1_TSH_ZH	rw	36	011 0110	00000000	
INT1_TSH_ZL	rw	37	011 0111	00000000	
INT1_DURATION	rw	38	011 1000	00000000	

Registers marked as *Reserved* must not be changed. The writing to those registers may cause permanent damages to the device.

The content of the registers that are loaded at boot should not be changed. They contain the factory calibration values. Their content is automatically restored when the device is powered-up.

## 7 Register description

The device contains a set of registers which are used to control its behavior and to retrieve acceleration data. The registers address, made of 7 bits, is used to identify them and to write the data through serial interface.

### 7.1 WHO\_AM\_I (0Fh)

**Table 19. WHO\_AM\_I register**

1	1	0	1	0	0	1	1
---	---	---	---	---	---	---	---

Device identification register.

### 7.2 CTRL\_REG1 (20h)

**Table 20. CTRL\_REG1 register**

DR1	DR0	BW1	BW0	PD	Zen	Yen	Xen
-----	-----	-----	-----	----	-----	-----	-----

**Table 21. CTRL\_REG1 description**

<b>DR1-DR0</b>	Output Data Rate selection. Refer to <a href="#">Table 22</a>
<b>BW1-BW0</b>	Bandwidth selection. Refer to <a href="#">Table 22</a>
<b>PD</b>	Power down mode enable. Default value: 0 (0: power down mode, 1: normal mode or sleep mode)
<b>Zen</b>	Z axis enable. Default value: 1 (0: Z axis disabled; 1: Z axis enabled)
<b>Yen</b>	Y axis enable. Default value: 1 (0: Y axis disabled; 1: Y axis enabled)
<b>Xen</b>	X axis enable. Default value: 1 (0: X axis disabled; 1: X axis enabled)

**DR<1:0>** is used to set ODR selection. **BW <1:0>** is used to set Bandwidth selection.

In the following table are reported all frequency resulting in combination of DR / BW bits.

**Table 22. DR and BW configuration setting**

DR <1:0>	BW <1:0>	ODR [Hz]	Cut-Off
00	00	100	12.5
00	01	100	25
00	10	100	25
00	11	100	25

**Table 22. DR and BW configuration setting (continued)**

DR <1:0>	BW <1:0>	ODR [Hz]	Cut-Off
01	00	200	12.5
01	01	200	25
01	10	200	50
01	11	200	70
10	00	400	20
10	01	400	25
10	10	400	50
10	11	400	110
11	00	800	30
11	01	800	35
11	10	800	50
11	11	800	110

Combination of **PD**, **Zen**, **Yen**, **Xen** are used to set device in different modes (power down / normal / sleep mode) according with the following table.

**Table 23. Power mode selection configuration**

Mode	PD	Zen	Yen	Xen
Power down	0	-	-	-
Sleep	1	0	0	0
Normal	1	-	-	-

## 7.3 CTRL\_REG2 (21h)

**Table 24. CTRL\_REG2 register**

0 <sup>(1)</sup>	0 <sup>(1)</sup>	HPM1	HPM1	HPCF3	HPCF2	HPCF1	HPCF0
------------------	------------------	------	------	-------	-------	-------	-------

1. Value loaded at boot. This value must not be changed

**Table 25. CTRL\_REG2 description**

HPM1- HPM0	High Pass filter Mode Selection. Default value: 00 Refer to <a href="#">Table 26</a>
HPCF3- HPCF0	High Pass filter Cut Off frequency selection Refer to <a href="#">Table 28</a>

**Table 26. High pass filter mode configuration**

HPM1	HPM0	High Pass filter Mode
0	0	Normal mode (reset reading HP_RESET_FILTER)
0	1	Reference signal for filtering
1	0	Normal mode
1	1	Autoreset on interrupt event

**Table 27. High pass filter cut off frequency configuration [Hz]**

HPCF3	ODR= 100 Hz	ODR= 200 Hz	ODR= 400 Hz	ODR= 800 Hz
0000	8	15	30	56
0001	4	8	15	30
0010	2	4	8	15
0011	1	2	4	8
0100	0.5	1	2	4
0101	0.2	0.5	1	2
0110	0.1	0.2	0.5	1
0111	0.05	0.1	0.2	0.5
1000	0.02	0.05	0.1	0.2
1001	0.01	0.02	0.05	0.1

## 7.4 CTRL\_REG3 (22h)

**Table 28. CTRL\_REG1 register**

I1_Int1	I1_Boot	H_Lactive	PP_OD	I2_DRDY	I2_WTM	I2_ORun	I2_Empty
---------	---------	-----------	-------	---------	--------	---------	----------

**Table 29. CTRL\_REG3 description**

I1_Int1	Interrupt enable on INT1 pin. Default value 0. (0: Disable; 1: Enable)
I1_Boot	Boot status available on INT1. Default value 0. (0: Disable; 1: Enable)
H_Lactive	Interrupt active configuration on INT1. Default value 0. (0: High; 1:Low)
PP_OD	Push- Pull / Open drain. Default value: 0. (0: Push- Pull; 1: Open drain)
I2_DRDY	Date Ready on DRDY/INT2. Default value 0. (0: Disable; 1: Enable)
I2_WTM	FIFO Watermark interrupt on DRDY/INT2. Default value: 0. (0: Disable; 1: Enable)
I2_ORun	FIFO Overrun interrupt on DRDY/INT2 Default value: 0. (0: Disable; 1: Enable)
I2_Empty	FIFO Empty interrupt on DRDY/INT2. Default value: 0. (0: Disable; 1: Enable)

## 7.5 CTRL\_REG4 (23h)

**Table 30. CTRL\_REG4 register**

BDU	BLE	FS1	FS0	-	ST1	ST0	SIM
-----	-----	-----	-----	---	-----	-----	-----

**Table 31. CTRL\_REG4 description**

<b>BDU</b>	Block Data Update. Default value: 0 (0: continuous update; 1: output registers not updated until MSB and LSB reading)
<b>BLE</b>	Big/Little Endian Data Selection. Default value 0. (0: Data LSB @ lower address; 1: Data MSB @ lower address)
<b>FS1-FS0</b>	Full Scale selection. Default value: 00 (00: 250 dps; 01: 500 dps; 10: 2000 dps; 11: 2000 dps)
<b>ST1-ST0</b>	Self Test Enable. Default value: 00 (00: Self Test Disabled; Other: See <a href="#">Table</a> )
<b>SIM</b>	SPI Serial Interface Mode selection. Default value: 0 (0: 4-wire interface; 1: 3-wire interface).

**Table 32. Self test mode configuration**

ST1	ST0	Self test mode
0	0	Normal mode
0	1	Self test 0 (+) <sup>(1)</sup>
1	0	--
1	1	Self test 1 (-) <sup>(1)</sup>

1. DST sign (absolute value in [Table 4](#))

## 7.6 CTRL\_REG5 (24h)

**Table 33. CTRL\_REG5 register**

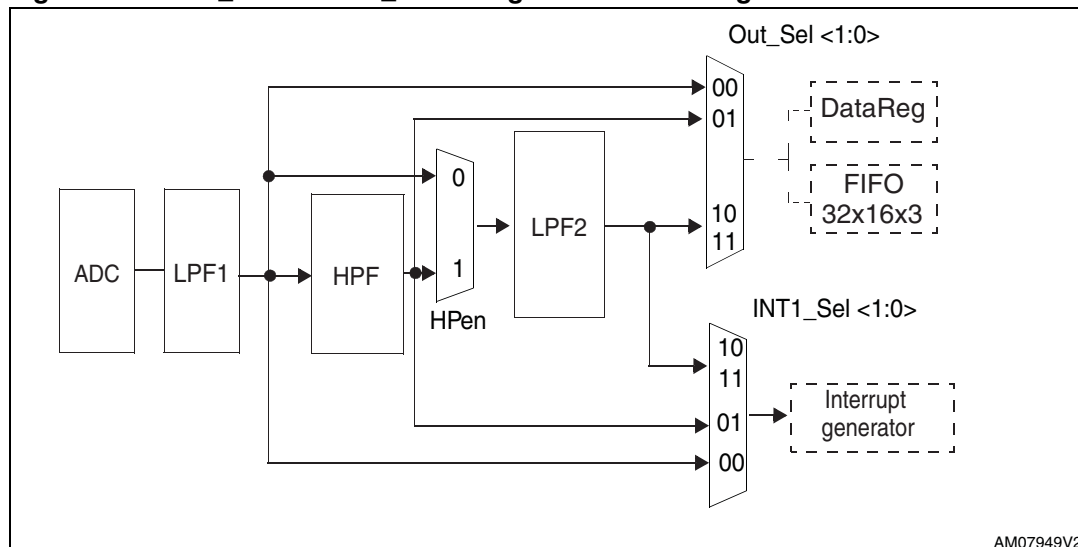
BOOT	FIFO_EN	--	HPen	INT1_Sel1	INT1_Sel0	Out_Sel1	Out_Sel0
------	---------	----	------	-----------	-----------	----------	----------

**Table 34. CTRL\_REG5 description**

<b>BOOT</b>	Reboot memory content. Default value: 0 (0: normal mode; 1: reboot memory content)
<b>FIFO_EN</b>	FIFO enable. Default value: 0 (0: FIFO disable; 1: FIFO Enable)
<b>HPen</b>	High Pass filter Enable. Default value: 0 (0: HPF disabled; 1: HPF enabled. See <a href="#">Figure 20</a> )
<b>INT1_Sel1-INT1_Sel0</b>	INT1 selection configuration. Default value: 0 (See <a href="#">Figure 20</a> )
<b>Out_Sel1-Out_Sel1</b>	Out selection configuration. Default value: 0 (See <a href="#">Figure 20</a> )



Figure 19. INT1\_Sel and Out\_Sel configuration block diagram



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Table 35. Out\_Sel configuration setting

Hpen	OUT_SEL1	OUT_SEL0	Description
x	0	0	Data in DataReg and FIFO are non-high-pass-filtered
x	0	1	Data in DataReg and FIFO are high-pass-filtered
0	1	x	Data in DataReg and FIFO are low-pass-filtered by LPF2
1	1	x	Data in DataReg and FIFO are high-pass and low-pass-filtered by LPF2

Table 36. INT\_SEL configuration setting

Hpen	INT_SEL1	INT_SEL2	Description
x	0	0	Non-high-pass-filtered data are used for interrupt generation
x	0	1	High-pass-filtered data are used for interrupt generation
0	1	x	Low-pass-filtered data are used for interrupt generation
1	1	x	High-pass and low-pass-filtered data are used for interrupt generation

## 7.7 REFERENCE/DATACAPTURE (25h)

**Table 37. REFERENCE register**

Ref7	Ref6	Ref5	Ref4	Ref3	Ref2	Ref1	Ref0
------	------	------	------	------	------	------	------

**Table 38. REFERENCE register description**

Ref 7-Ref0	Reference value for Interrupt generation. Default value: 0
------------	--

## 7.8 OUT\_TEMP (26h)

**Table 39. OUT\_TEMP register**

Temp7	Temp6	Temp5	Temp4	Temp3	Temp2	Temp1	Temp0
-------	-------	-------	-------	-------	-------	-------	-------

**Table 40. OUT\_TEMP register description**

Temp7-Temp0	Temperature data.
-------------	-------------------

## 7.9 STATUS\_REG (27h)

**Table 41. STATUS\_REG register**

ZYXOR	ZOR	YOR	XOR	ZYXDA	ZDA	YDA	XDA
-------	-----	-----	-----	-------	-----	-----	-----

**Table 42. STATUS\_REG description**

ZYXOR	X, Y, Z -axis data overrun. Default value: 0 (0: no overrun has occurred; 1: new data has overwritten the previous one before it was read)
ZOR	Z axis data overrun. Default value: 0 (0: no overrun has occurred; 1: a new data for the Z-axis has overwritten the previous one)
YOR	Y axis data overrun. Default value: 0 (0: no overrun has occurred; 1: a new data for the Y-axis has overwritten the previous one)
XOR	X axis data overrun. Default value: 0 (0: no overrun has occurred; 1: a new data for the X-axis has overwritten the previous one)
ZYXDA	X, Y, Z -axis new data available. Default value: 0 (0: a new set of data is not yet available; 1: a new set of data is available)
ZDA	Z axis new data available. Default value: 0 (0: a new data for the Z-axis is not yet available; 1: a new data for the Z-axis is available)
YDA	Y axis new data available. Default value: 0 (0: a new data for the Y-axis is not yet available; 1: a new data for the Y-axis is available)
XDA	X axis new data available. Default value: 0 (0: a new data for the X-axis is not yet available; 1: a new data for the X-axis is available)

**7.10 OUT\_X\_L (28h), OUT\_X\_H (29h)**

X-axis angular rate data. The value is expressed as two's complement.

**7.11 OUT\_Y\_L (2Ah), OUT\_Y\_H (2Bh)**

Y-axis angular rate data. The value is expressed as two's complement.

**7.12 OUT\_Z\_L (2Ch), OUT\_Z\_H (2Dh)**

Z-axis angular rate data. The value is expressed as two's complement.

**7.13 FIFO\_CTRL\_REG (2Eh)****Table 43. REFERENCE register**

FM2	FM1	FM0	WTM4	WTM3	WTM2	WTM1	WTM0
-----	-----	-----	------	------	------	------	------

**Table 44. REFERENCE register description**

FM2-FM0	FIFO mode selection. Default value: 00 (see <a href="#">Table</a> )
WTM4-WTM0	FIFO threshold. Watermark level setting

**Table 45. FIFO mode configuration**

FM2	FM1	FM0	FIFO mode
0	0	0	Bypass mode
0	0	1	FIFO mode
0	1	0	Stream mode
0	1	1	Stream-to-FIFO mode
1	0	0	Bypass-to-Stream mode

**7.14 FIFO\_SRC\_REG (2Fh)****Table 46. FIFO\_SRC register**

WTM	OV RN	EMPTY	FSS4	FSS3	FSS2	FSS1	FSS0
-----	-------	-------	------	------	------	------	------

**Table 47. FIFO\_SRC register description**

WTM	Watermark status. (0: FIFO filling is lower than WTM level; 1: FIFO filling is equal or higher than WTM level)
OV RN	Overflow bit status. (0: FIFO is not completely filled; 1: FIFO is completely filled)

**Table 47. FIFO\_SRC register description (continued)**

EMPTY	FIFO empty bit. ( 0: FIFO not empty; 1: FIFO empty)
FSS4-FSS1	FIFO stored data level

## 7.15 INT1\_CFG (30h)

**Table 48. INT1\_CFG register**

AND/OR	LIR	ZHIE	ZLIE	YHIE	YLIE	XHIE	XLIE
--------	-----	------	------	------	------	------	------

**Table 49. INT1\_CFG description**

AND/OR	AND/OR combination of Interrupt events. Default value: 0 (0: OR combination of interrupt events 1: AND combination of interrupt events)
LIR	Latch Interrupt Request. Default value: 0 (0: interrupt request not latched; 1: interrupt request latched) Cleared by reading INT1_SRC reg.
ZHIE	Enable interrupt generation on Z high event. Default value: 0 (0: disable interrupt request; 1: enable interrupt request on measured accel. value higher than preset threshold)
ZLIE	Enable interrupt generation on Z low event. Default value: 0 (0: disable interrupt request; 1: enable interrupt request on measured accel. value lower than preset threshold)
YHIE	Enable interrupt generation on Y high event. Default value: 0 (0: disable interrupt request; 1: enable interrupt request on measured accel. value higher than preset threshold)
YLIE	Enable interrupt generation on Y low event. Default value: 0 (0: disable interrupt request; 1: enable interrupt request on measured accel. value lower than preset threshold)
XHIE	Enable interrupt generation on X high event. Default value: 0 (0: disable interrupt request; 1: enable interrupt request on measured accel. value higher than preset threshold)
XLIE	Enable interrupt generation on X low event. Default value: 0 (0: disable interrupt request; 1: enable interrupt request on measured accel. value lower than preset threshold)

Configuration register for Interrupt source.

## 7.16 INT1\_SRC (31h)

**Table 50. INT1\_SRC register**

0	IA	ZH	ZL	YH	YL	XH	XL
---	----	----	----	----	----	----	----

**Table 51. INT1\_SRC description**

IA	Interrupt active. Default value: 0 (0: no interrupt has been generated; 1: one or more interrupts have been generated)
ZH	Z high. Default value: 0 (0: no interrupt, 1: Z High event has occurred)
ZL	Z low. Default value: 0 (0: no interrupt; 1: Z Low event has occurred)
YH	Y high. Default value: 0 (0: no interrupt, 1: Y High event has occurred)
YL	Y low. Default value: 0 (0: no interrupt, 1: Y Low event has occurred)
XH	X high. Default value: 0 (0: no interrupt, 1: X High event has occurred)
XL	X low. Default value: 0 (0: no interrupt, 1: X Low event has occurred)

Interrupt source register. Read only register.

Reading at this address clears INT1\_SRC IA bit (and eventually the interrupt signal on INT1 pin) and allows the refreshment of data in the INT1\_SRC register if the latched option was chosen.

## 7.17 INT1\_THS\_XH (32h)

**Table 52. INT1\_THS\_XH register**

-	THSX14	THSX13	THSX12	THSX11	THSX10	THSX9	THSX8
---	--------	--------	--------	--------	--------	-------	-------

**Table 53. INT1\_THS\_XH description**

THSX14 - THSX9	Interrupt threshold. Default value: 0000 0000
----------------	---

## 7.18 INT1\_THS\_XL (33h)

**Table 54. INT1\_THS\_XL register**

THSX7	THSX6	THSX5	THSX4	THSX3	THSX2	THSX1	THSX0
-------	-------	-------	-------	-------	-------	-------	-------

**Table 55. INT1\_THS\_XL description**

THSX7 - THSX0	Interrupt threshold. Default value: 0000 0000
---------------	---

## 7.19 INT1\_THS\_YH (34h)

**Table 56. INT1\_THS\_YH register**

-	THSY14	THSY13	THSY12	THSY11	THSY10	THSY9	THSY8
---	--------	--------	--------	--------	--------	-------	-------

**Table 57. INT1\_THS\_YH description**

THSY14 - THSY9	Interrupt threshold. Default value: 0000 0000
----------------	---

## 7.20 INT1\_THS\_YL (35h)

**Table 58. INT1\_THS\_YL register**

THSR7	THSY6	THSY5	THSY4	THSY3	THSY2	THSY1	THSY0
-------	-------	-------	-------	-------	-------	-------	-------

**Table 59. INT1\_THS\_YL description**

THSY7 - THSY0	Interrupt threshold. Default value: 0000 0000
---------------	---

## 7.21 INT1\_THS\_ZH (36h)

**Table 60. INT1\_THS\_ZH register**

-	THSZ14	THSZ13	THSZ12	THSZ11	THSZ10	THSZ9	THSZ8
---	--------	--------	--------	--------	--------	-------	-------

**Table 61. INT1\_THS\_ZH description**

THSZ14 - THSZ9	Interrupt threshold. Default value: 0000 0000
----------------	---

## 7.22 INT1\_THS\_ZL (37h)

**Table 62. INT1\_THS\_ZL register**

THSZ7	THSZ6	THSZ5	THSZ4	THSZ3	THSZ2	THSZ1	THSZ0
-------	-------	-------	-------	-------	-------	-------	-------

**Table 63. INT1\_THS\_ZL description**

THSZ7 - THSZ0	Interrupt threshold. Default value: 0000 0000
---------------	---

## 7.23 INT1\_DURATION (38h)

**Table 64. INT1\_DURATION register**

WAIT	D6	D5	D4	D3	D2	D1	D0
------	----	----	----	----	----	----	----

**Table 65. INT1\_DURATION description**

WAIT	WAIT enable. Default value: 0 (0: disable; 1: enable)
D6 - D0	Duration value. Default value: 000 0000

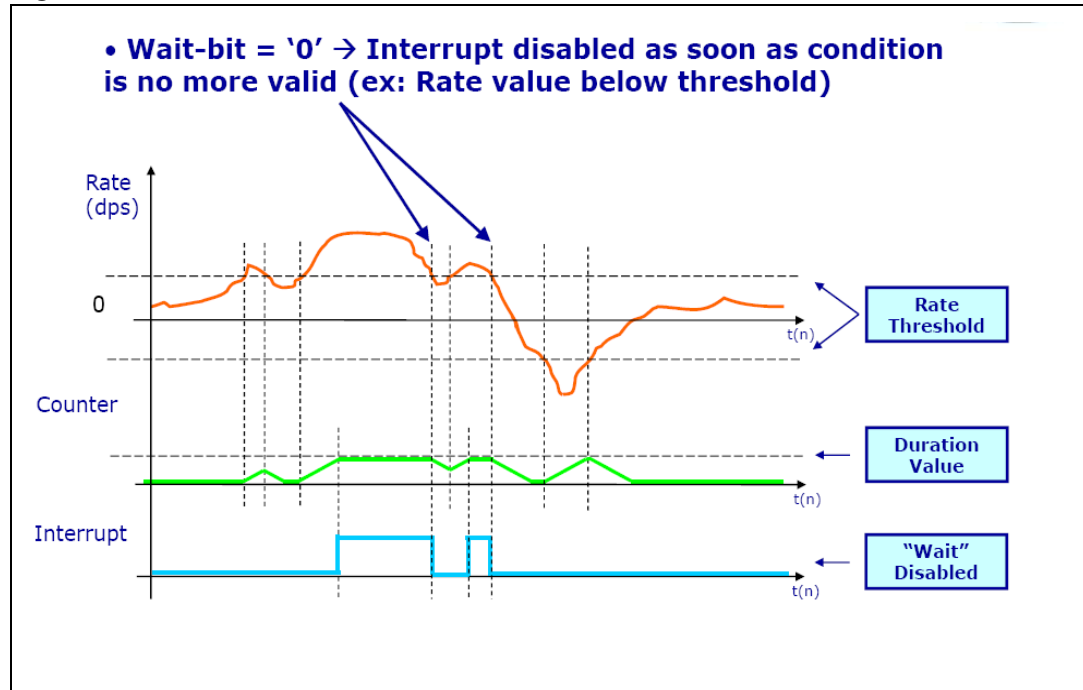
**D6 - D0** bits set the minimum duration of the Interrupt event to be recognized. Duration steps and maximum values depend on the ODR chosen.

**WAIT** bit has the following meaning:

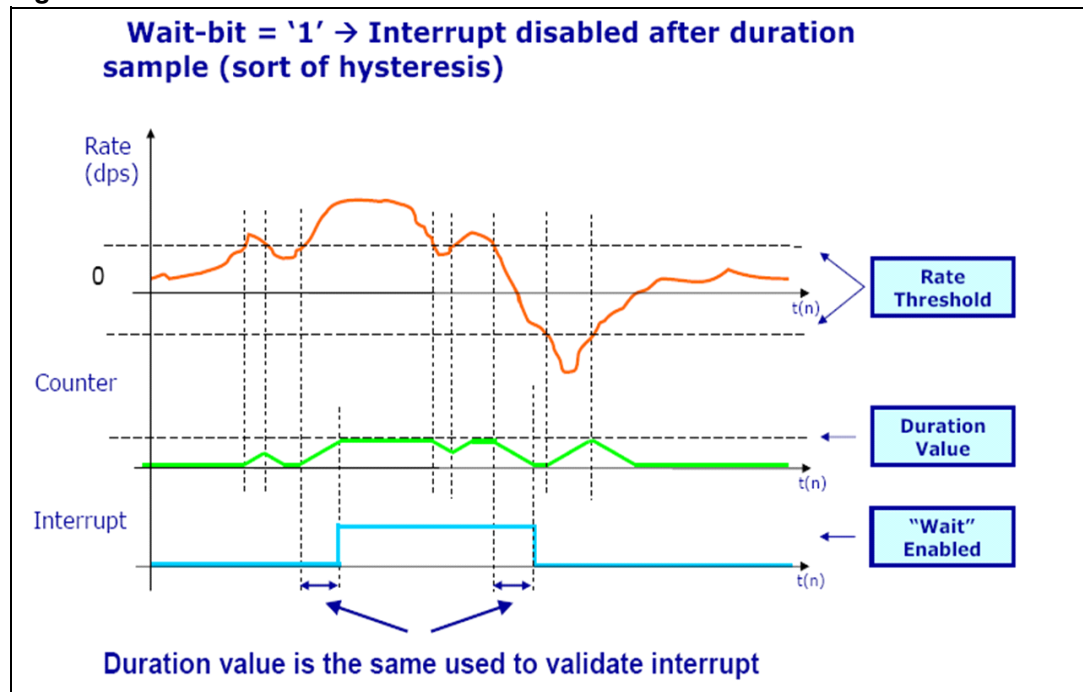
Wait = '0': the interrupt falls immediately if signal crosses the selected threshold

Wait = '1': if signal crosses the selected threshold, the interrupt falls only after the duration has counted number of samples at the selected data rate, written into the duration counter register.

**Figure 20. Wait disabled**



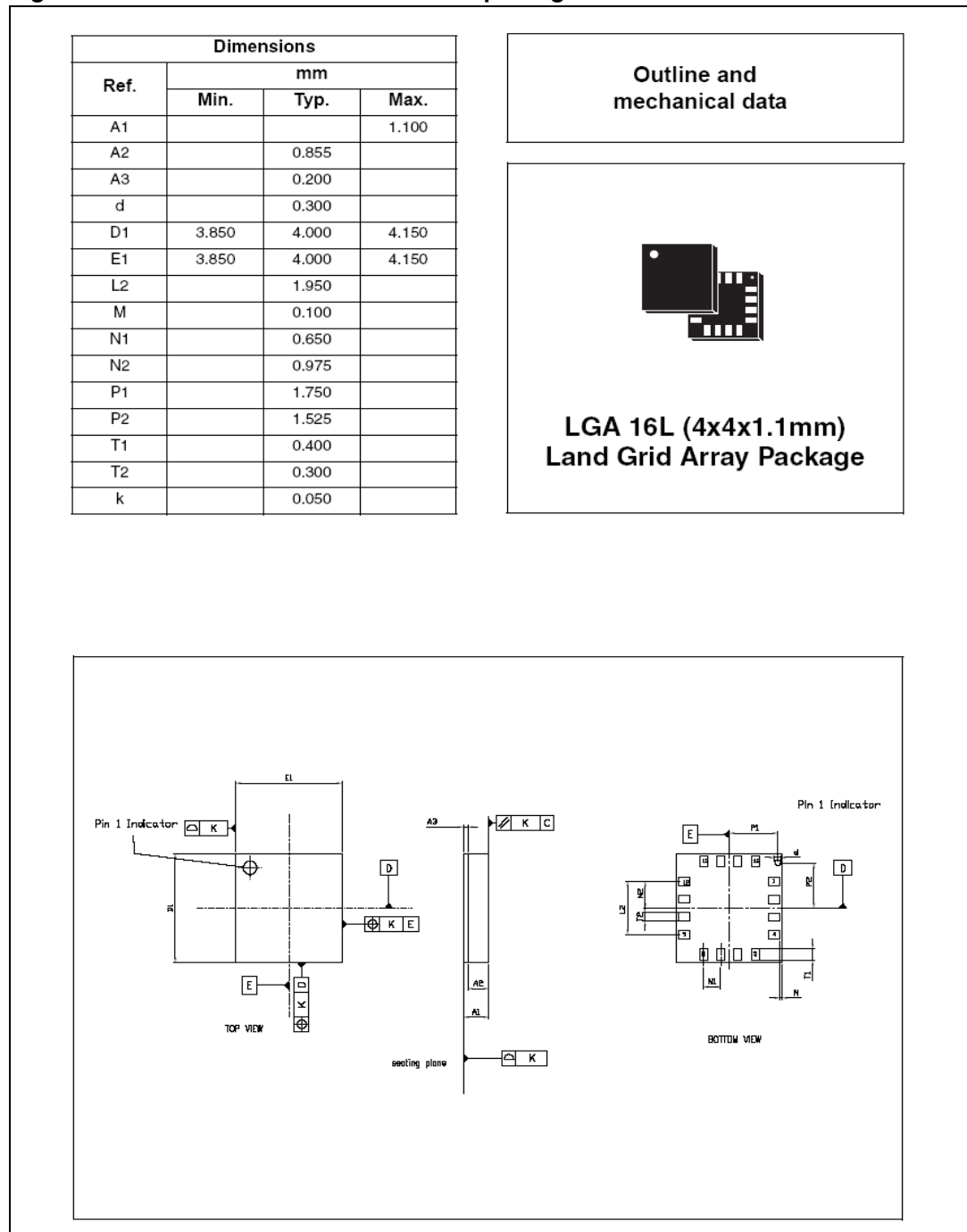
**Figure 21. Wait enabled**



## 8 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Figure 22. LGA-16: mechanical data and package dimensions**





## 9 Revision history

**Table 66. Document revision history**

Date	Revision	Changes
01-Apr-2010	1	Initial release.
03-Sep-2010	2	Complete datasheet review.
22-Dec-2010	3	Inserted <a href="#">Section 6: Output register mapping</a> and <a href="#">Section 7: Register description</a> .

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